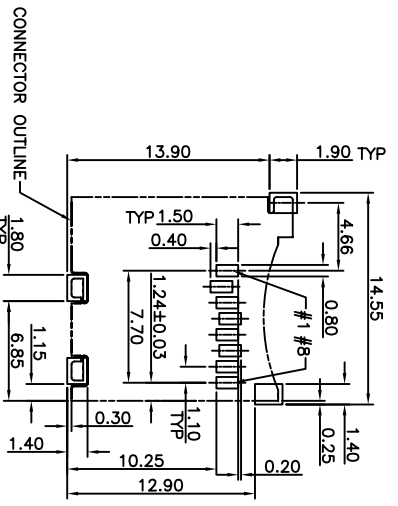
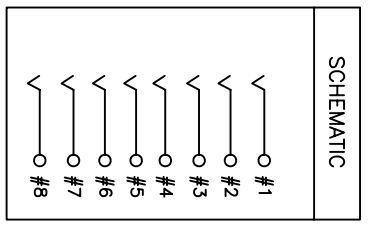
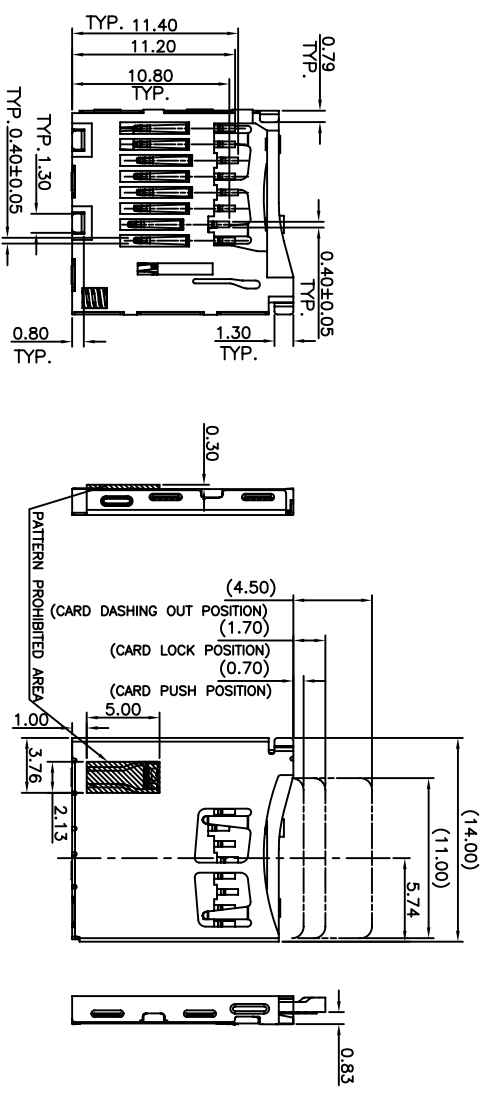
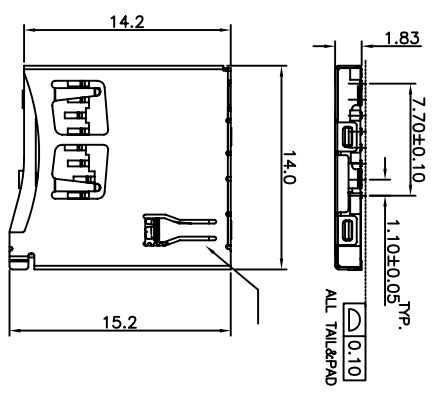
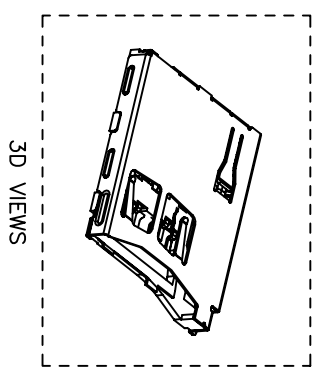


REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PRODUCT RELEASE	劉木達	2007.11.26
B	ADD HALOGEN FREE MARK ECN NO:R020204	孫一中	2008.11.27



NOTES:  
 1. MATERIAL: HOUSING:HIGH TEMPERATURE THERMOPLASTIC. UL94V-0-BLACK  
 SLIDE:HIGH TEMPERATURE THERMOPLASTIC. UL94V-0-BLACK  
 SHELL:STAINLESS STEEL.  
 CONTACT:COPPER ALLOY.  
 DETECT PIN: COPPER ALLOY.  
 LOCK PIN:STAINLESS STEEL.  
 2. PLATED: CONTACT:20u" Min. Au PLATING IN CONTACT AREA;  
 1~3u" Min Au PLEATED OVERALL,  
 50u" Ni UNDERPLATED OVERALL.  
 DETECT PIN:1u" Min. Au PLATED OVER ALL  
 50u" Min. Ni UNDERPLATED OVERALL .  
 3.ELECTRICAL CHARACTERISTIC:  
 CONNECT RESISTANCE:40 MILLIONMS/PIN Max.  
 INSULATION RESISTANCE:1000 MEGAOHMS Min.  
 VOLTAGE WITHSTAND:500V AC for 1minute  
 4.MECHANICAL CHARACTERISTIC:  
 CONTACT MATING FORCE:3kgf Max.  
 CONTACT UNMATING FORCE:100gf Min.  
 DURABILITY:3000 CYCLES  
 5. SOLDER HEAT RESISTANCE:REFLOW SOLDERING 260° FOR 10 SEC.  
 6. TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.  
 7. HALOGEN FREE PRODUCT IDENTIFICATION MARK ON PRODUCT:  
 8. HALOGEN FREE PRODUCT IDENTIFICATION LOGO ON PACKING:  
 9. FOR REFLOW SOLDERING LEAD-FREE PROCESS.



Pin No.	Name	Type	DESCRIPTION
1	DAT2	I/O/PP	Data Line [bit2]
2	CD/DAT3	I/O/PP	Card Detect Data Line [bit3]
3	CMD	PP	Command Response
4	VDD	S	Supply Voltage
5	CLK	I	Clock
6	VSS	S	Supply Voltage Ground
7	DATO	I/O/PP	Data Line [bit0]
8	DAT1	I/O/PP	Data Line [bit1]

NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
UNLESS OTHERWISE SPECIFIED TOLERANCES				
DECIMALS: ANGLES:				
X	:±0.5	X	:±2°	
X.X	:±0.3	X.X	:±1°	
X.XX	:±0.2			
TITLE	TRANS FLASH PUSH/PUSH TYPE			
DWN	孫一中	PART NO.	2CA-0005-002	
CHKD	劉木達	SCALE	2:1 UNIT: mm	
APVD	羅文生	SIZE: A3	SHEET: 10F1	REV: B
CUSTOMER COPY				

Singatron Enterprise Co., Ltd.  
 信晉企業股份有限公司